

**Amendments to the Specification:**

Please replace the second full paragraph on page 11, lines 11-23, with the following amended paragraph:

--In this initial stroke S (I), since the contact between the substrate 7 and the mask plate 12 is in a state under pressure from below at the squeegeeing time, the mask plate 12 moves nearly in accordance with the descent of the substrate 7, and the upper surface of the substrate 7 has not started the separation from the lower surface of the mask plate 12 yet. Therefore, the decrease in viscosity of the solder cream 9 is produced in the entire range of the substrate 7. Namely, in the start of the plate separating operation in which the substrate 7 descends by the initial stroke ~~(S)~~ S (I), it is possible to improve uniformly plate separativeness when the solder cream 9 separates from the pattern hole 12a throughout the entire printing range of the substrate 7.--